

SOT2265-1

WFBGA169, very-very-thin profile fine-pitch ball grid array package, 169 terminals, 0,5 mm pitch, 7 mm x 7 mm x 0.695 mm body

12 February 2026

Package information



1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WFBGA169
Package style descriptive code	WFBGA (very-very-thin profile fine-pitch ball grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	09-02-2026
Manufacturer package code	98ASA02230D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.85	7	7.15	mm
package width	6.85	7	7.15	mm
seated height	-	0.695	0.8	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	169	-	



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2 Package outline

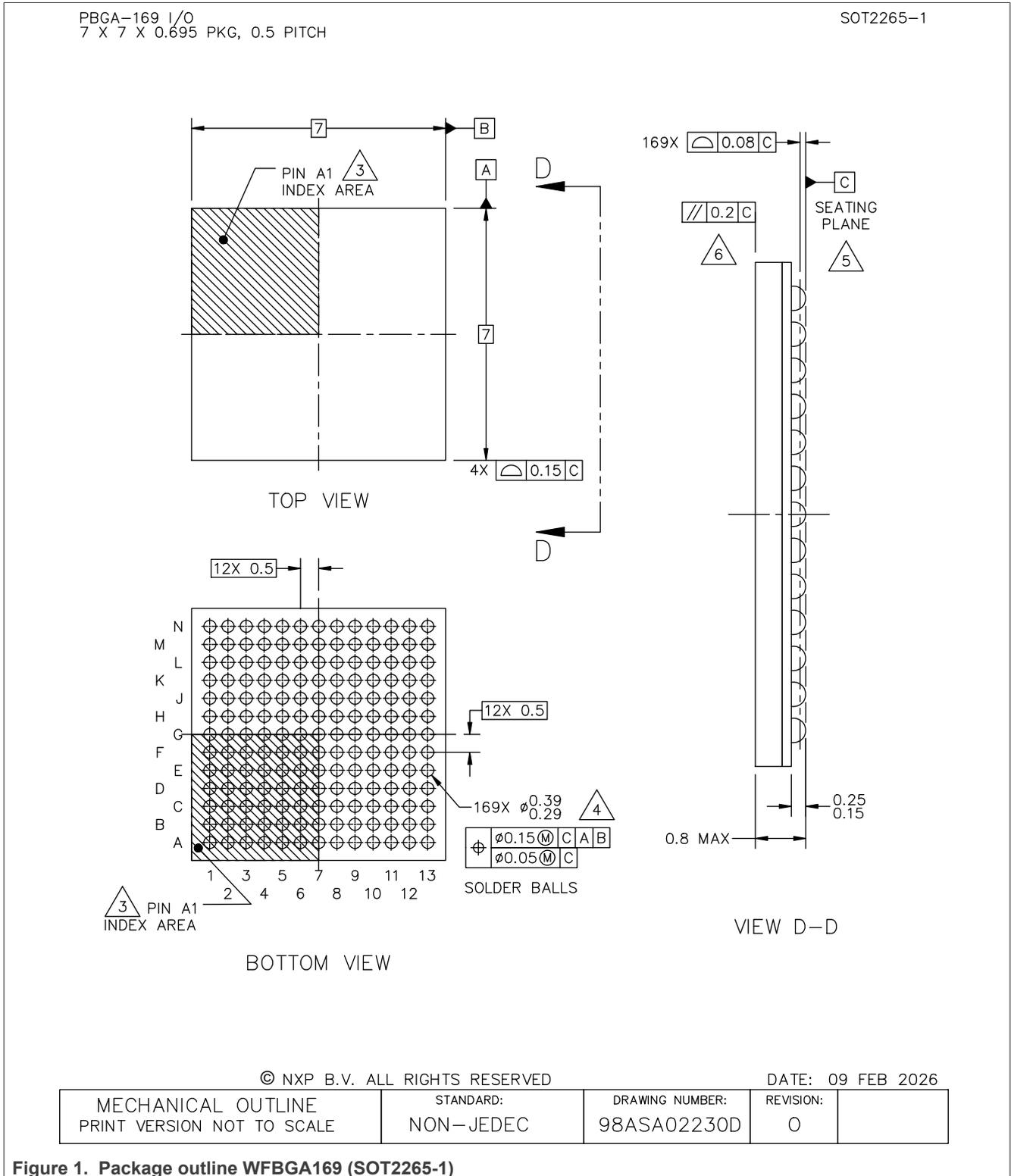
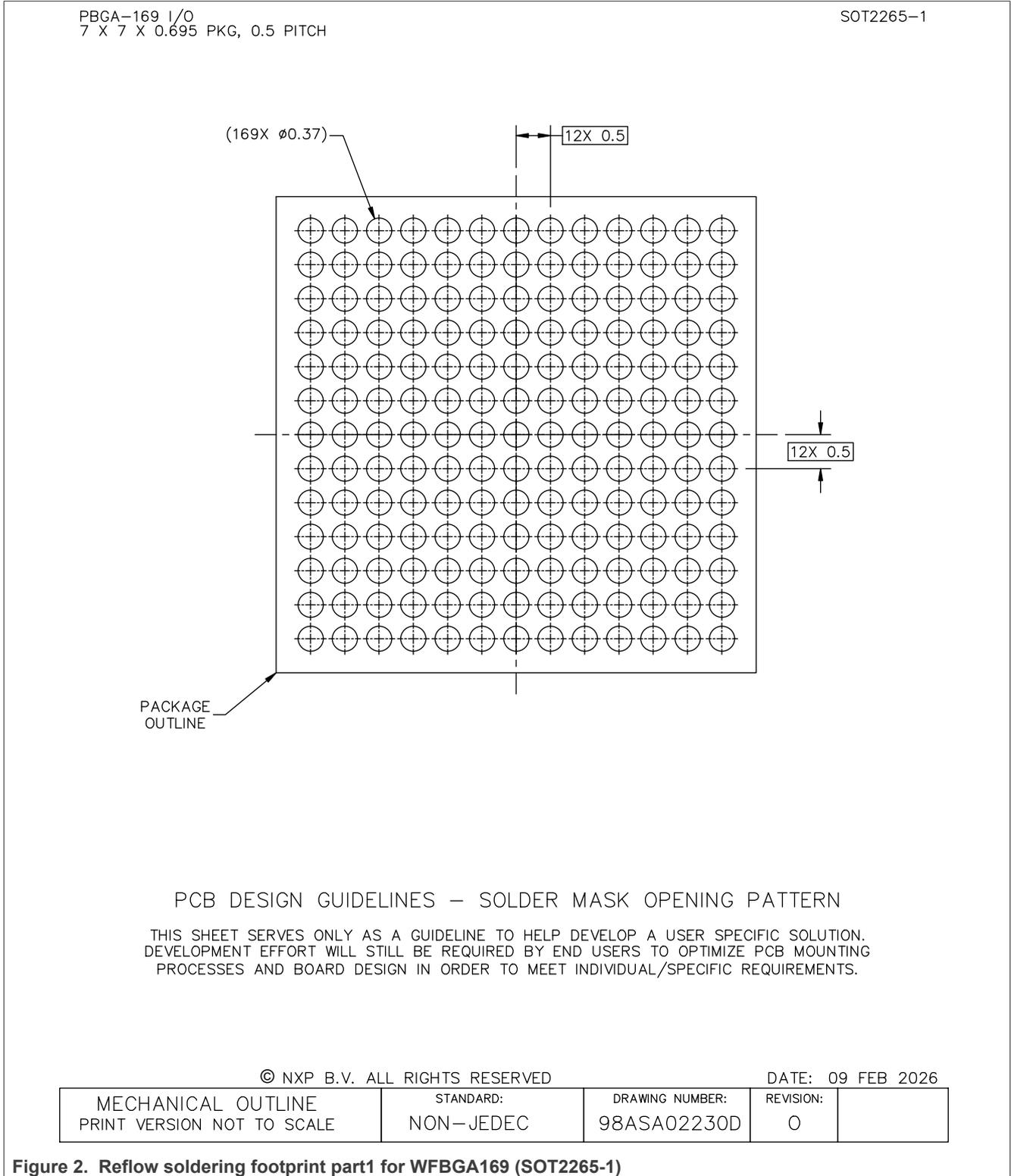


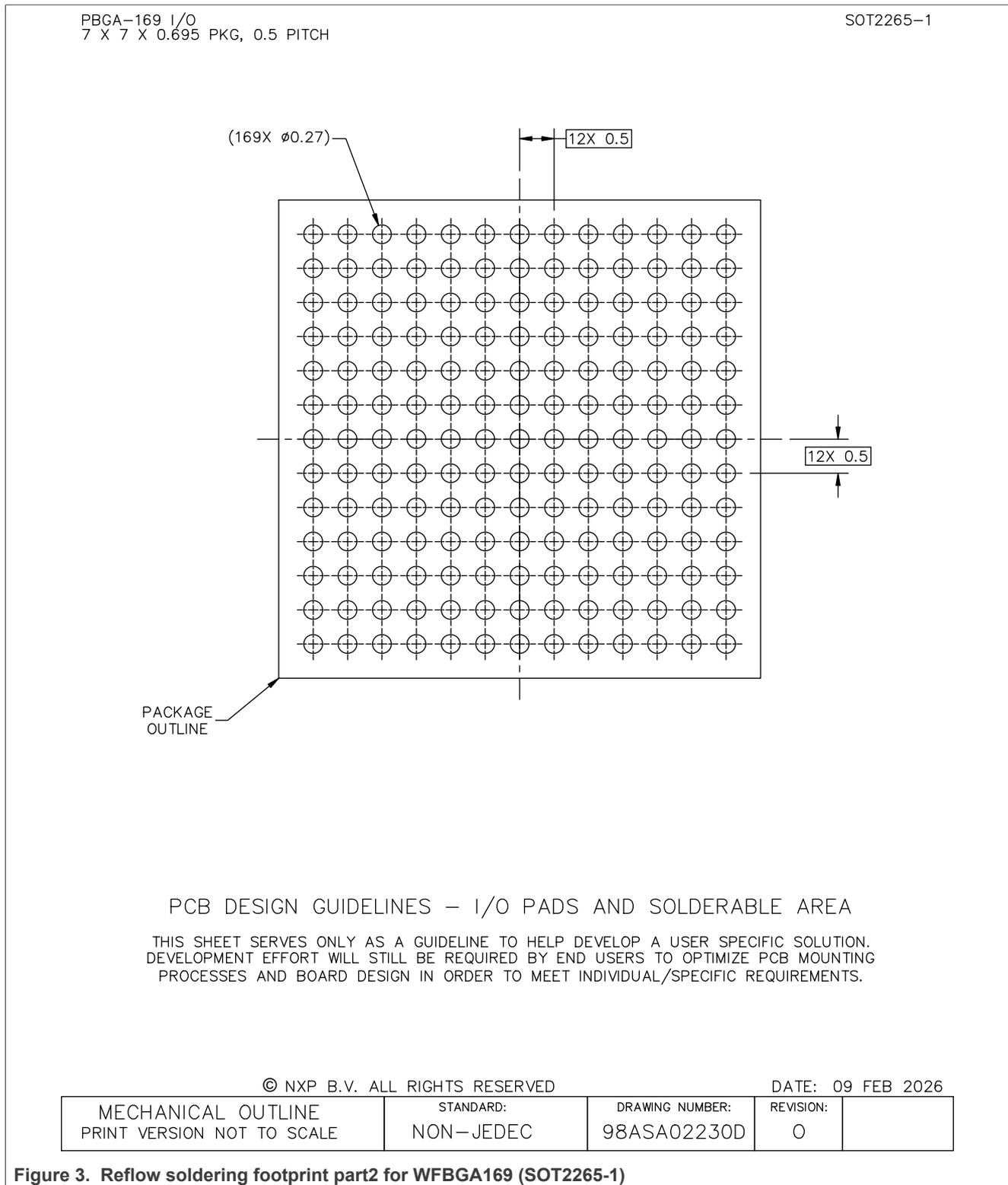
Figure 1. Package outline WFBGA169 (SOT2265-1)

WFBGA169, very-very-thin profile fine-pitch ball grid array package, 169 terminals, 0,5 mm pitch, 7 mm x 7 mm x 0.695 mm body

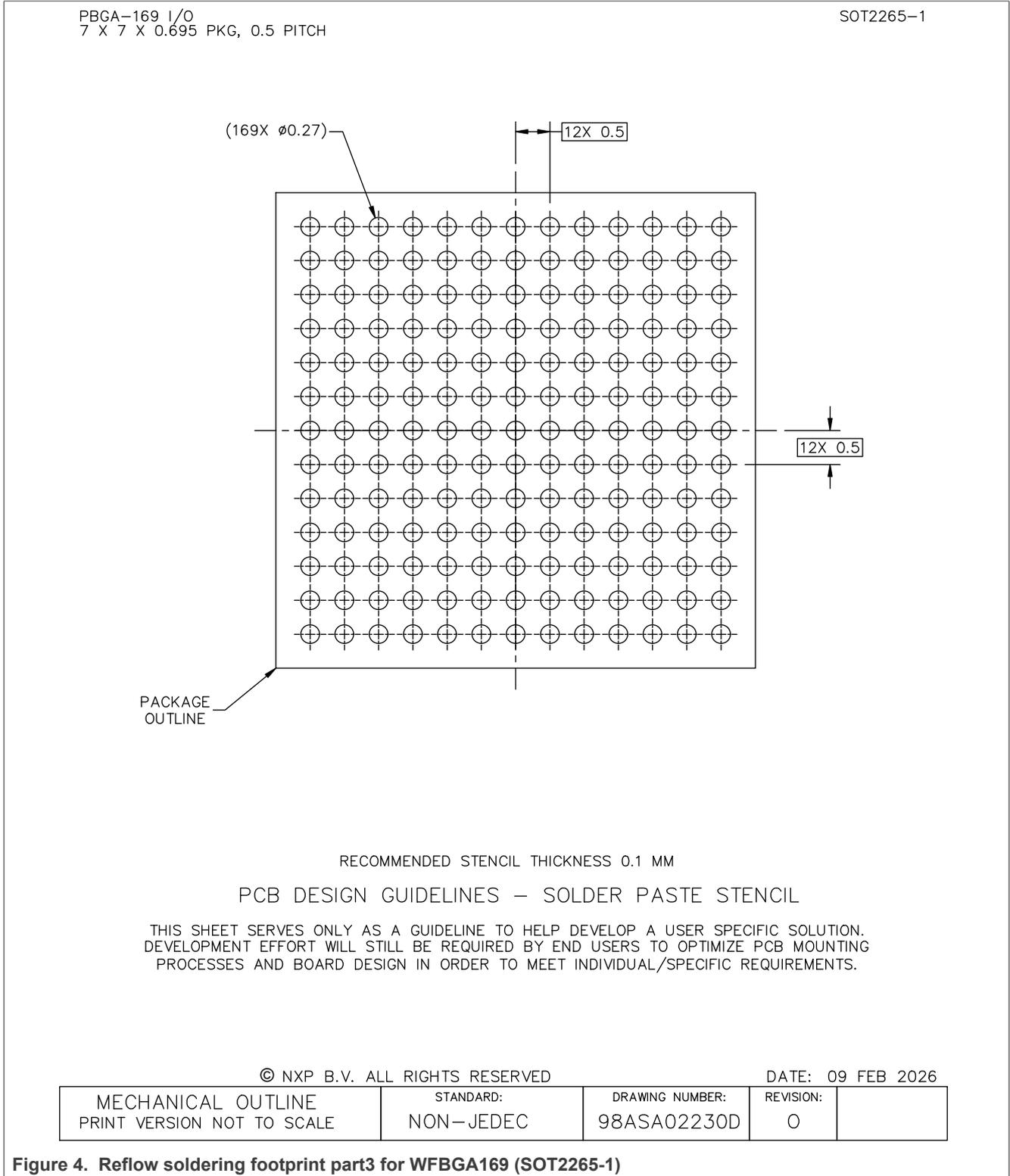
3 Soldering



WFBGA169, very-very-thin profile fine-pitch ball grid array package, 169 terminals, 0,5 mm pitch, 7 mm x 7 mm x 0.695 mm body



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PBGA-169 I/O
7 X 7 X 0.695 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 09 FEB 2026

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02230D	REVISION: 0	
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Figure 5. Package outline note WFBGA169 (SOT2265-1)

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